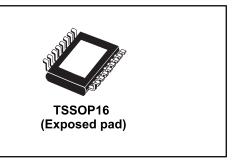
STP04CM05



4-bit constant current power-LED sink driver

Datasheet - production data



Features

- 4 constant current output channels
- Adjustable output current through one external resistor
- Can be driven by a 3.3 V microcontroller
- Serial data IN/parallel data OUT
- Output current: 80-400 mA
- 20 V of output driving capability
- 30 MHz clock frequency
- UVLO (under voltage lockout) and POR (power ON reset)
- TSD, thermal shutdown, output off when junction temperature exceeds limit
- Operating free-air temperature range -40° to 125 °C
- ESD protection 2.5 kV HBM, 200 V MM
- Available in high thermal TSSOP exposed pad

Description

The STP04CM05 is a high-power LED driver and 4-bit shift register designed for Power-LED applications.

The STP04CM05 contains a 4-bit serial IN, parallel OUT shift register that feeds a 4-bit D-type storage register. In the output stage, four regulated current sources were designed to provide 80-400 mA constant current to drive high power LEDs.

The STP04CM05 guarantees 20 V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 30 MHz, also satisfies the system requirements which include high volume data transmission.

The STP04CM05 is well suited for very high brightness displays and special lighting applications.

The STP04CM05 is offered in TSSOP16 exposed pad packages.

Table 1: Device summary

Order code	Package	Packing
STP04CM05XTTR	TSSOP16 exposed pad (tape and reel)	2500 parts per reel

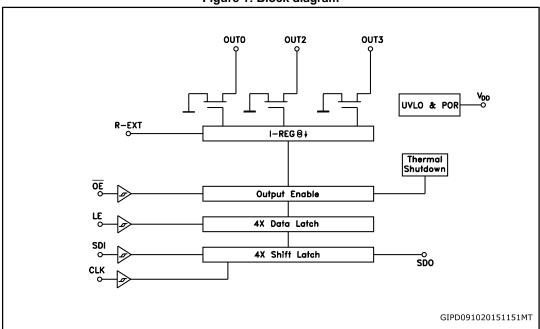
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STP04CM05 Internal schematic

1 Internal schematic

Figure 1: Block diagram

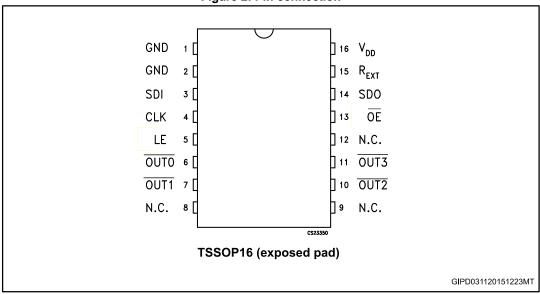


Pin settings STP04CM05

2 Pin settings

2.1 Pin connection

Figure 2: Pin connection





The exposed pad should be attached to a metal land electrically isolated or connected to ground.

2.2 Pin description

Table 2: Pin description

TSSOP16 exposed pad pin N°	Symbol Name and function		
1, 2	GND	Ground terminal	
3	SDI	Serial data input terminal	
4	CLK	Clock input terminal	
5	LE	Latch input terminal	
6	OUT 0	Output terminal	
7	OUT 1	Output terminal	
8, 9, 12	N.C.	Not connected	
10	OUT 2	Output terminal	
11	OUT 3	Output terminal	
13	OE	Output enable input terminal (active low)	
14	SDO	Serial data out terminal	
15	R-EXT	Constant current programming	
16	V_{DD}	5 V supply voltage terminal	

STP04CM05 Maximum rating

3 Maximum rating

Stressing the device above the rating listed in the "absolute maximum ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 3: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DD}	Supply voltage	0 to 7	V
Vo	Output voltage	-0.5 to 20	V
lo	Output current	500	mA
Vı	Input voltage	-0.4 to V _{DD} +0.4	V
I _{GND}	GND terminal current	2000	mA
f _{CLK}	Clock frequency	50	MHz
T _{OPR}	Operating temperature range	-40 to +125	°C
T _{STG}	Storage temperature range	-55 to +150	°C

3.1 Thermal data

Table 4: Thermal data

Symbol	Parameter	TSSOP16 exposed pad	Unit
RthJA	Thermal resistance junction-ambient	37.5 ⁽¹⁾	°C/W

Notes

⁽¹⁾ Using the PCB multi-layer JEDEC Standard test boards.

Maximum rating STP04CM05

3.2 Recommended operating conditions

Table 5: Recommended operating conditions

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
V _{DD}	Supply voltage		3.3	5.0	5.5	V
Vo	Output voltage				19	V
lo	Output current	OUTn V _{DD} = 5 V	80		400	mA
Іон	Output current	Serial-OUT			+1	mA
loL	Output current	Serial-OUT			-1	mA
ViH	Input voltage		0.7 V _{DD}		V _{DD} +0.3	V
VIL	Input voltage		-0.3		0.3 V _{DD}	V
t	t _{wEN} OE pulse width	$V_{DD} = 5 \text{ V}, I_{O} = 350 \text{ mA}$	80	50		ns
LWEN		$V_{DD} = 3.3 \text{ V}, I_{O} = 350 \text{ mA}$	250	150		
twLAT	LE pulse width		8	4		ns
t _{wCLK}	CLK pulse width		8.5	7.5		ns
tsetup(d)	Setup time for DATA	$V_{DD} = 3.0 \text{ to } 3.6 \text{ V}$	8.5	7.5		ns
thold(D)	Hold time for DATA	VDD = 3.0 to 3.6 V	8.5	7.5		ns
tsetup(L)	Setup time for LATCH		8.5	7.0		ns
thold(E)	Hold time for ENABLE		8.5	7.0		ns
fclk	Clock frequency	Cascade operation (1)			30	MHz
Topr	Operating temperature range		-40		+125	°C

Notes:

⁽¹⁾ If multiple devices are cascaded, it may not be possible achieve the maximum data transfer. Please consider the timing conditions carefully.

4 Electrical characteristics

 $T_A = 25$ °C, unless otherwise specified.

Table 6: Current accuracy

Output valtage	Current a	accuracy	Output augrent
Output voltage	Between bits	Between ICs	Output current
≥ 1.4 V	Typ. ± 1%	± 6%	80 to 400 mA

Table 7: Electrical characteristics (V_{DD} = 3.3 to 5 V)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
VIH	Input voltage high level		0.7 V _{DD}		V_{DD}	V
VIL	Input voltage low level		GND		0.3 V _{DD}	V
I _{OH}	Output leakage current	V _{OH} = 19 V			10	μΑ
VoL	Output voltage (serial-OUT)	I _{OL} = 1 mA			0.4	V
Vон	Output voltage (serial-OUT)	Iон = -1 mA	V _{DD} - 0.4 V			V
I _{OL1}	Output current	$V_0 = 0.3 \text{ VR}_{EXT} = 980 \Omega$	75.2	80	84.8	mA
I _{OL2}	Output current	V _O = 1.2 VR _{EXT} = 190 kΩ	376	400	424	mA
∆l _{OL1}	Output current error between bit	$V_0 = 0.3 \text{ VR}_{\text{EXT}} = 980 \Omega$ $I_0 = 80 \text{ mA}$		1	1.5	%
Δl _{OL2}	(all output ON)	$V_0 = 1.2 \text{ VR}_{\text{EXT}} = 190 \Omega$ $I_0 = 400 \text{ mA}$		1	1.5	%
R _{SIN(up)}	Pull-up resistor		150	300	600	kΩ
R _{SIN(down)}	Pull-down resistor		100	200	400	kΩ
I _{DD(OFF1)}		R _{EXT} = OPEN OUT 0 to 3 = OFF		1	1.5	
I _{DD(OFF2)}	Supply current (OFF)	R_{EXT} = 980 Ω OUT 0 to 3 = OFF		3.8	6	
I _{DD(OFF3)}	,	R_{EXT} = 190 Ω OUT 0 to 3 = OFF		14	18.5	mA
I _{DD(ON1)}	Supply current (ON)	R_{EXT} = 980 Ω OUT 0 to 3 = ON		4.0	6.0	
I _{DD(ON2)}	Cappiy current (ON)	R_{EXT} = 190 Ω OUT 0 to 3 = ON		14.5	19	

Table 8: Switching characteristics (V_{DD} = 3.3 to 5 V)

Table 8: Switching characteristics (VDD = 3.3 to 5 V)							
Symbol	Parameter	Test con	ditions	Min.	Тур.	Max.	Unit
	Propagation delay time,		$V_{DD} = 3.3 \text{ V}$	-	290	377	
t _{PLH1}	CLK- OUTn LE = H,						
	/ OE = L		$V_{DD} = 5 V$	-	200	260	ns
	Propagation delay time,		V _{DD} = 3.3 V	-	200	260	
t PLH2	LE- OUTn , / OE = L		$V_{DD} = 5 \text{ V}$	-	140	180	ns
	Propagation delay time,		V _{DD} = 3.3 V	-	240	310	ns
t _{PLH3}	/ OE - OUTn , LE = H		V _{DD} = 5 V	-	170	220	
	Propagation delay time,		V _{DD} = 3.3 V	-	25	35	
t PLH	CLK-SDO		V _{DD} = 5 V	-	15	20	ns
	Propagation delay time,	D 500	$V_{DD} = 3.3 \text{ V}$	-	49	64	
t _{PHL1}	CLK- OUTn LE = H,	$R_L = 5.0 \Omega$ $C_L = 10 pF$					
/ OE =	/ OE = L	Io = 350 mA	$V_{DD} = 5 V$	-	36	47	ns
	Propagation delay time,	$R_{EXT} = 224 \Omega$ $V_L = 3.0 V$	V _{DD} = 3.3 V	-	39	51	
t _{PHL2}	$\overline{LE} - \overline{OUTn} \ , / \ \overline{OE} \ = L$	VL = 3.0 V	V _{DD} = 5 V	-	26	34	ns
t _{PHL3}	Propagation delay time, / OE - OUTn LE = H		V _{DD} = 3.3 V	-	48	62	ns
	7 32 33111 22 - 11		$V_{DD} = 5 V$	-	32	42	
t _{PHL}	Propagation delay time,		$V_{DD} = 3.3 \text{ V}$	-	30	39	
TPHL	CLK-SDO		$V_{DD} = 5 V$	-	19	25	ns
ton	Output rise time 10~90% of		$V_{DD} = 3.3 \text{ V}$	-	880	1150	
LON	voltage waveform		$V_{DD} = 5 \text{ V}$	-	616	800	ns
toff	Output fall time 90~10% of		$V_{DD} = 3.3 \text{ V}$	-	18	24	
WFF	voltage waveform		$V_{DD} = 5 \text{ V}$	-	14	18	ns
t _r	CLK rise time (1)	Vo = 5.0 V		-		5000	ns
t_f	CLK fall time (1)	$R_{EXT} = 224 \Omega$		-		5000	ns

Notes:

⁽¹⁾ In order to achieve high cascade data transfer, please consider tr/tf timings carefully.

5 Equivalent circuit and outputs

Figure 3: OE terminal

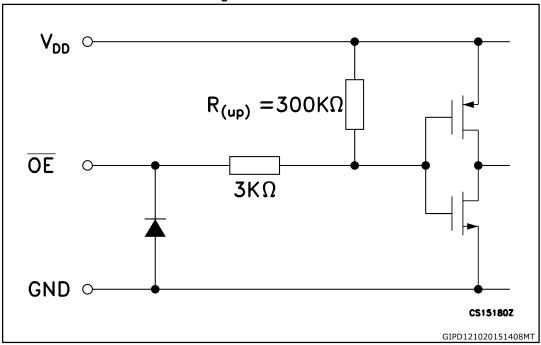


Figure 4: LE terminal

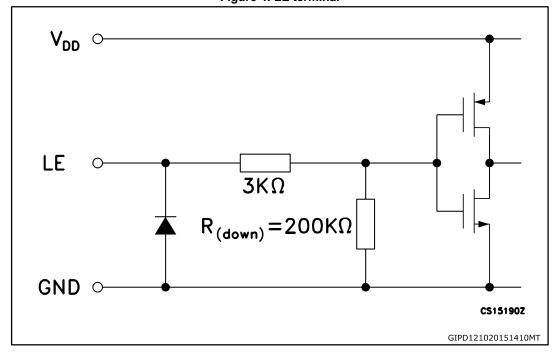


Figure 5: CLK, SDI terminal

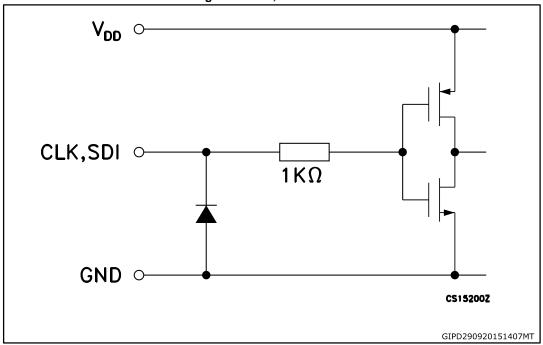
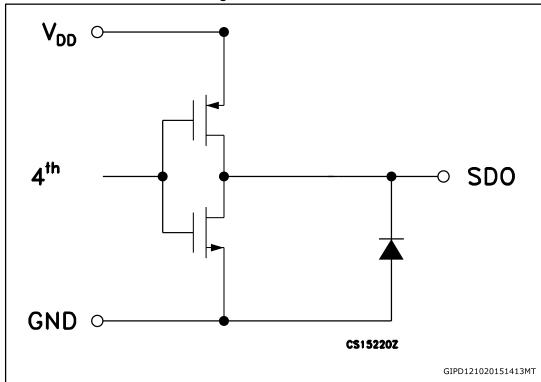


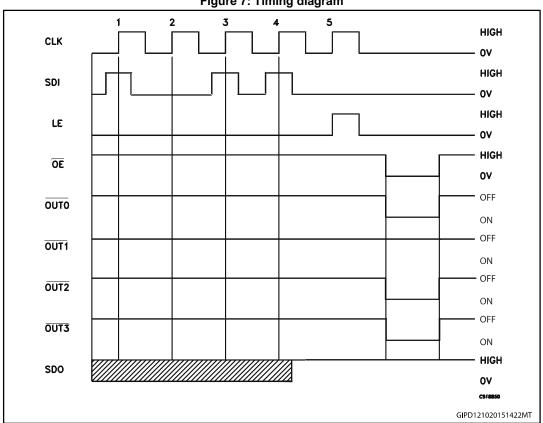
Figure 6: SDO terminal



Timing diagrams STP04CM05

Timing diagrams 6

Figure 7: Timing diagram

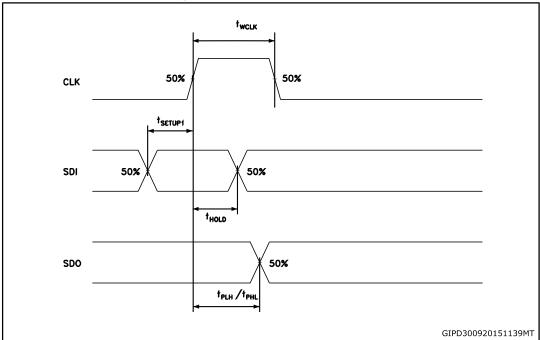




- 1 Latch and output enable are level sensitive and are not synchronized with risingor-falling edge of CLK signal.
- 2 When LE terminal is low level, the latch circuit hold previous set of data.
- 3 When LE terminal is high level, the latch circuit refresh new set of data from SDI chain.
- 4 When OE terminal is at low level, the output terminal Out 0 to Out 03 respond to data in the latch circuits, either '1' for ON or '0' for OFF.
- 5 When OE terminal is at high level, all output terminals will be switched OFF.

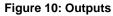
Timing diagrams STP04CM05

Figure 8: Clock, serial-in, serial-out

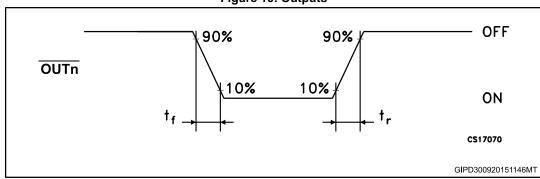


STP04CM05 Timing diagrams

Figure 9: Clock, serial-in, latch, enable, outputs 50% CLK SDI †SETUP2 50% 50% LE †_{WENA} ΌE 50% 50% †_{SETUP3} OUTn 50% t_{PHL1}/t_{PLH1} $t_{\rm PHL2}/t_{\rm PLH2}$



t_{PHL3}/t_{PLH3}



CS17060GIPD121020151426MT

Test circuit STP04CM05

7 Test circuit

Figure 11: DC characteristic

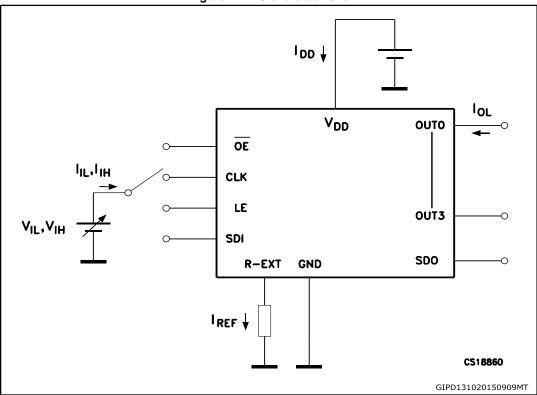
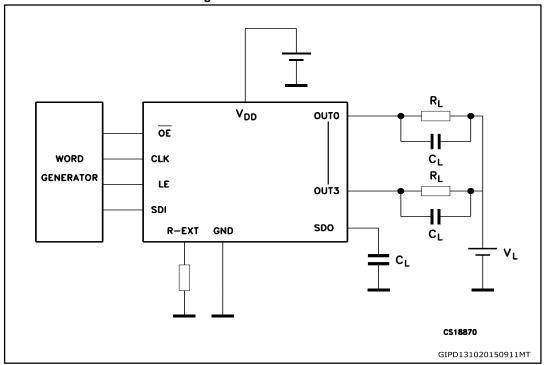
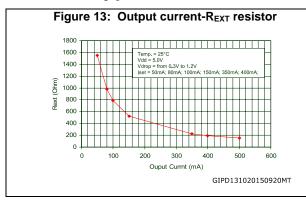


Figure 12: AC characteristic



8 Typical characteristics



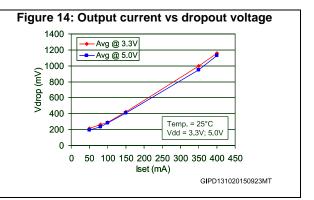


Figure 15: Output current vs ± ΔI_{OL}(%)

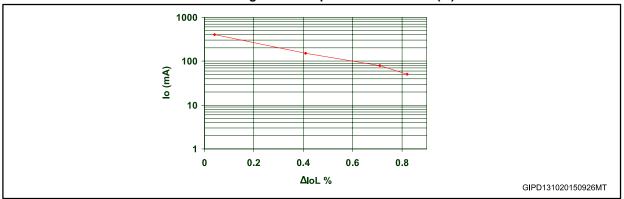
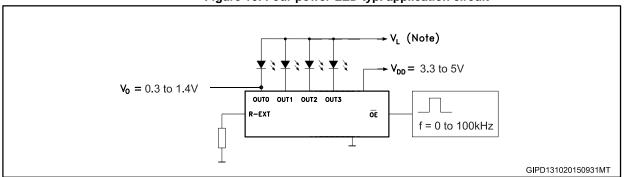


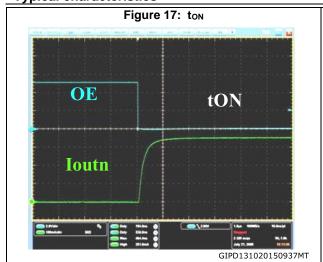
Figure 16: Four power-LED typ. application circuit

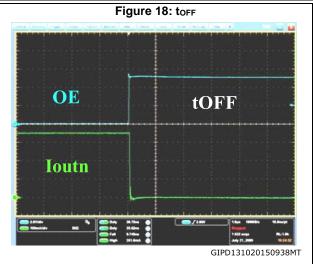


8

 V_L will be determined by the V_F of the LEDs.

Condition: $T_A = 25$ °C, $V_{dd} = 5$ V, $V_L = 3$ V, $R_{ext} = 227$ Ω .





9 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

9.1 TSSOP16 exposed pad package information

Figure 19: TSSOP16 exposed pad package outline

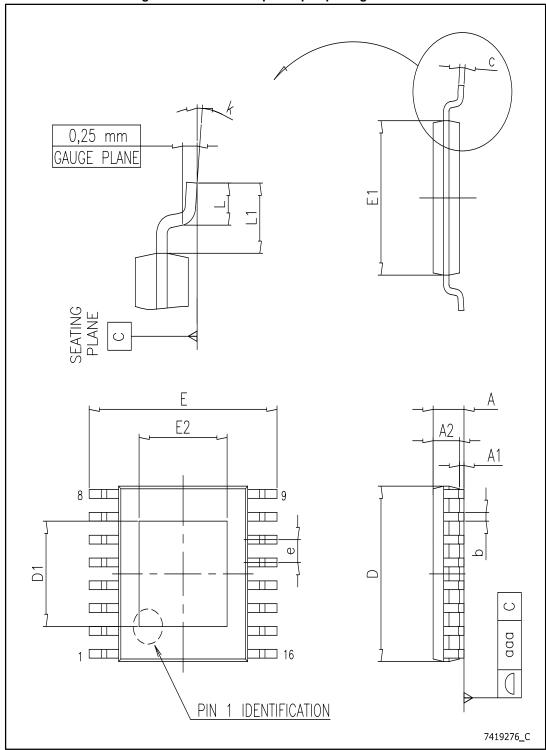


Table 9: TSSOP16 exposed pad package mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А			1.10
A1	0.05		0.15
A2	0.85	0.90	0.95
b	0.19		0.30
С	0.09		0.20
D		5.00	
D1		ACCORDING TO PAD SI	ZE
E		6.40	
E1	4.30	4.40	4.50
E2		ACCORDING TO PAD SI	ZE
е		0.65	
L	0.50	0.60	0.70
L1		1.00	
k			8
aaa			0.076

9.2 TSSOP16 exposed pad packing information

Figure 20: TSSOP16 exposed pad tape and reel outline

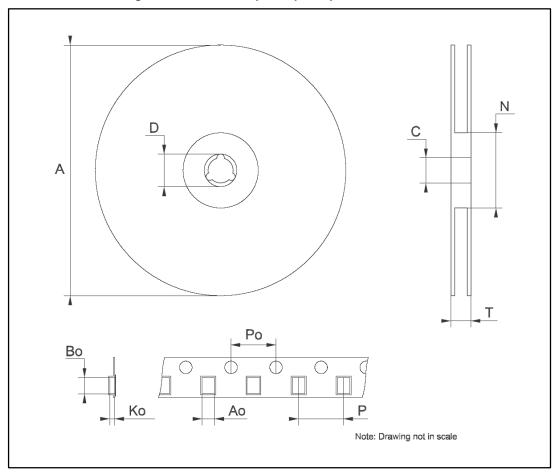


Table 10: TSSOP16 exposed pad packing mechanical data

Dim	Dim.				inch	
Dim.	Min.	Тур.	Max.	Min.	Тур.	Max.
А			330			12.992
С	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
Т			22.4			0.882
Ao	6.7		6.9	0.264		0.272
Во	5.3		5.5	0.209		0.217
Ko	1.6		1.8	0.063		0.071
Po	3.9		4.1	0.153		0.161
Р	7.9		8.1	0.311		0.319

STP04CM05 Revision history

10 Revision history

Table 11: Document revision history

Date	Revision	Changes
26-Nov-2007	1	Initial release
16-Jan-2008	2	Added: Figure 15 on page 15 and Figure 19 on page 17, Updated: Table 8 on page 8.
12-Mar-2008	3	Updated: Figure 8 on page 12.
23-Jun-2008	4	Updated: Table 1 on page 1, Figure 21 on page 20.
07-Jun-2010	5	Updated: Note: on page 4, Table 10 on page 19.
		Removed SO-14 package.
07-Jan-2016	6	Updated Figure 5: "CLK, SDI terminal".
		Minor text changes.

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